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(54) **Title:** MONITORING SYSTEM FOR DEPOSITION AND METHOD OF OPERATION THEREOF

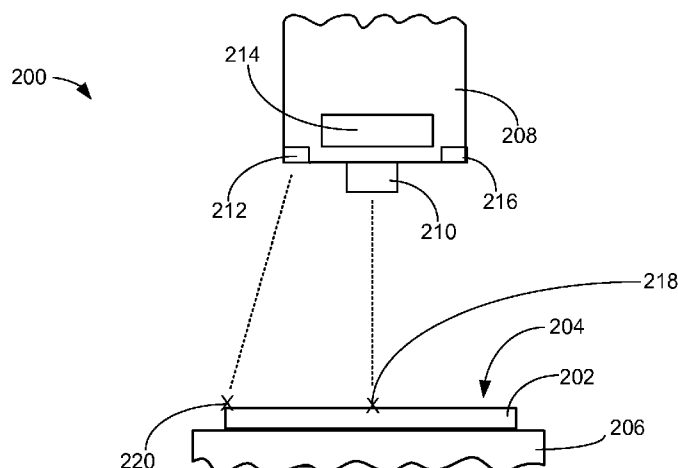


FIG. 2

(57) **Abstract:** A monitoring system and method of operation thereof includes: providing a substrate on a platform; performing a scan of the substrate; depositing a material layer on the substrate; monitoring a deposition thickness of the material layer; and generating an alert based on an error in the deposition thickness.